



#### Layout Guide:

1. C4靠近IC PIN1
2. Q2 MOS散熱Pad要大，可以用裸銅或條狀裸銅，散熱較佳。
3. IC的GND PIN與C4的GND端連接後再接到電源GND，不可和MOS GND端直接連接。
4. 10W以上功率應用，L1與Q2 MOS不可靠太近，防止溫度互相烤高。
5. Q2 MOS GND端與C1 GND端連接線儘量粗短。
6. L1/Q2/D1三元件連接端走線儘量粗短。

#### LED電流設定:

$$I-LED = 0.2V/R_p$$

$$R_p = R_{10} // R_{11} // R_{12} // R_{13} // R_{14} // R_{15}, R_{10} \sim R_{15} \text{ 電阻併聯}$$

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